- 3-State Outputs Drive Bus Lines or Buffer Memory Address Registers
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)
- Package Options Include Plastic Small-Outline Packages, Ceramic Chip Carriers, and Plastic and Ceramic DIPs

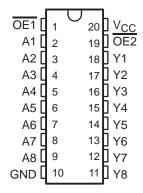
description

The 'F541 octal buffer/line driver is ideal for driving bus lines or buffering memory address registers. The device features inputs and outputs on opposite sides of the package to facilitate printed-circuit-board layout.

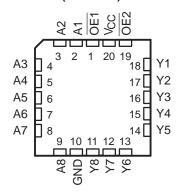
The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output enable (OE1 or OE2) input is high, all eight outputs are in the high-impedance state.

The SN54F541 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74F251 is characterized for operation from 0°C to 70°C.

SN54F541 ... J PACKAGE SN74F541 ... DW OR N PACKAGE (TOP VIEW)



SN54F541 . . . FK PACKAGE (TOP VIEW)



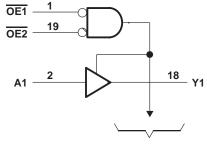
FUNCTION TABLE

	INPUTS	OUTPUT	
OE1	OE2	Α	Y
L	L	L	L
L	L	Н	н
Н	X	Χ	Z
Х	Н	Χ	Z

logic symbol†

1 ΕN 19 OE2 18 **A1** 3 17 **A2 Y2** 16 А3 **Y3** 5 15 Α4 6 14 Y5 **A5** 7 13 A6 **Y6** 12 **A7 Y7** 9 11 **Y8 A8**

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	
Input current range	–30 mA to 5 mA
Voltage range applied to any output in the disabled or power-off state	
Voltage range applied to any output in the high state	-0.5 V to V_{CC}
Current into any output in the low state: SN54F541	96 mA
SN74F541	128 mA
Operating free-air temperature range: SN54F541	–55°C to 125°C
SN74F541	0°C to 70°C
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		s	N54F54	1	SN74F541			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.8			0.8	V
ΙK	Input clamp current			-18			-18	mA
lOH	High-level output current			- 12			– 15	mA
l _{OL}	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0		70	°C



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

NOTE 1: The input voltage ratings may be exceeded provided the input current ratings are observed.

SDFS021A - D3126, JANUARY 1989 - REVISED OCTOBER 1993

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			N54F54	I	S	UNIT			
PARAMETER	1531	CONDITIONS	MIN	TYP [†]	MAX	MIN	TYP	MAX	UNII	
VIK	$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2			-1.2	V	
		$I_{OH} = -3 \text{ mA}$	2.4	3.3		2.4	3.3			
\/a	V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2	3.2					V	
VOH		$I_{OH} = -15 \text{ mA}$				2	3.1		V	
	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$				2.7				
Va	V _{OL} V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$		0.38	0.55				V	
VOL		$I_{OL} = 64 \text{ mA}$					0.42	0.55	v	
lozh	V _{CC} = 5.5 V,	$V_0 = 2.7 \text{ V}$			50			50	μΑ	
lozL	V _{CC} = 5.5 V,	V _O = 0.5 V			-50			-50	μΑ	
ΙĮ	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA	
lіН	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20			20	μΑ	
Ι _{ΙL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.5 V			- 0.6			- 0.6	mA	
los [‡]	$V_{CC} = 5.5 \text{ V},$	VO = 0	-100		-225	-100		-225	mA	
	V _{CC} = 5.5 V	Outputs high		28	35		28	35		
Icc		Outputs low		62	75		62	75	mA	
		Outputs disabled		40	55		40	55		

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics (see Note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _I R _I	CC = 5 V _ = 50 pl _ = 500 s _ = 25°C	F, Ω,	C _L R _L	= 50 pF = 500 Ω		V,	UNIT
				′F541		SN54	F541	SN74	F541	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	Any A	V	1.5	3.3	5.5	1	6.5	1.5	6	6 ns
^t PHL	Ally A	Ť	1.5	2.7	5.5	1	6.5	1.5	6	115
^t PZH	ŌĒ	V	3	5.8	8	1.7	10	2.5	9.5	ns
^t PZL	OE	OE Y	3.5	6.1	8.5	2.2	10	3	9.5	115
^t PHZ	ŌĒ	Y	1.5	3.4	6	1	7	1.5	6.5	ns
t _{PLZ}	OL .		1.5	2.9	5.5	1	7.5	1.5	6	115

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. NOTE 2: Load circuits and waveforms are shown in Section 1.



[‡] Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9175301M2A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9175301M2A SNJ54F541FK
5962-9175301MRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9175301MR A SNJ54F541J
SN74F541DW	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	0 to 70	F541
SN74F541DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F541
SN74F541DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	F541
SN74F541N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F541N
SN74F541N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74F541N
SN74F541NSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F541
SN74F541NSR.A	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	74F541
SNJ54F541FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9175301M2A SNJ54F541FK
SNJ54F541FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9175301M2A SNJ54F541FK
SNJ54F541J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9175301MR A SNJ54F541J
SNJ54F541J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9175301MR A SNJ54F541J

⁽¹⁾ **Status:** For more details on status, see our product life cycle.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

PACKAGE OPTION ADDENDUM

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(4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54F541, SN74F541:

Catalog: SN74F541

Military: SN54F541

NOTE: Qualified Version Definitions:

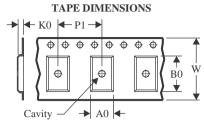
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

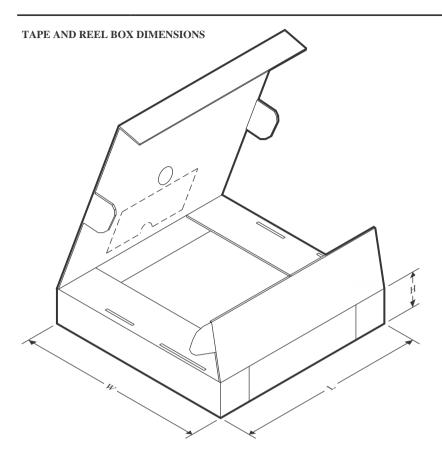


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74F541DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74F541NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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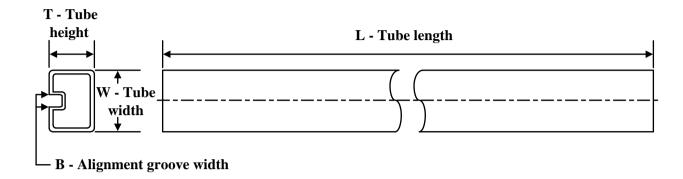
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74F541DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74F541NSR	SOP	NS	20	2000	356.0	356.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9175301M2A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74F541N	N	PDIP	20	20	506	13.97	11230	4.32
SN74F541N.A	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54F541FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54F541FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN

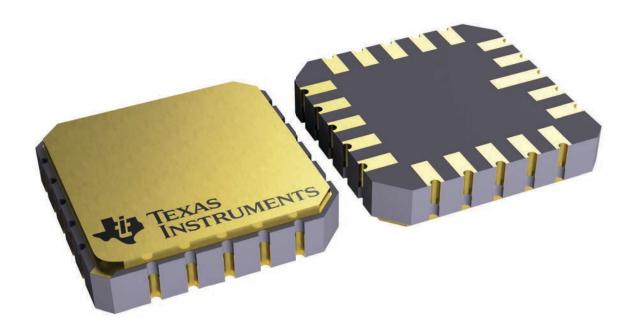


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



INSTRUMENTS www.ti.com

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

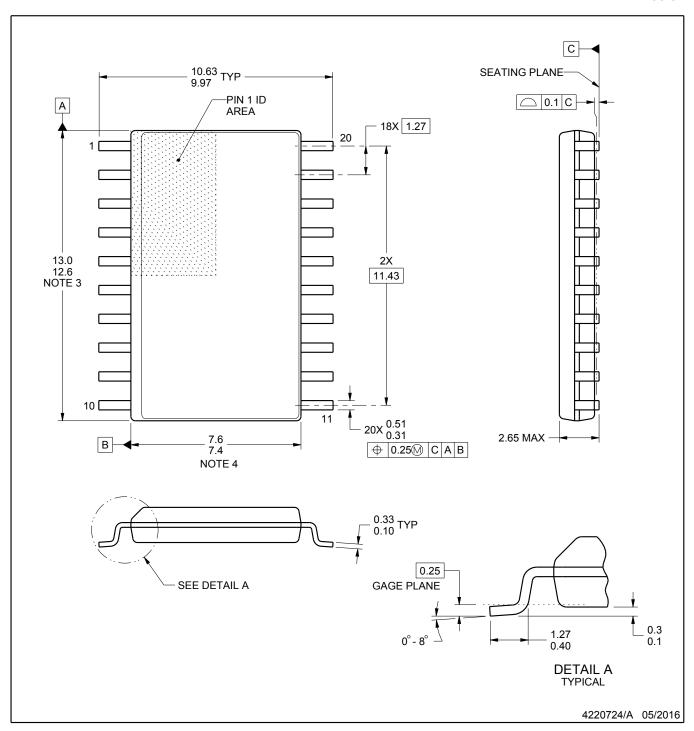


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



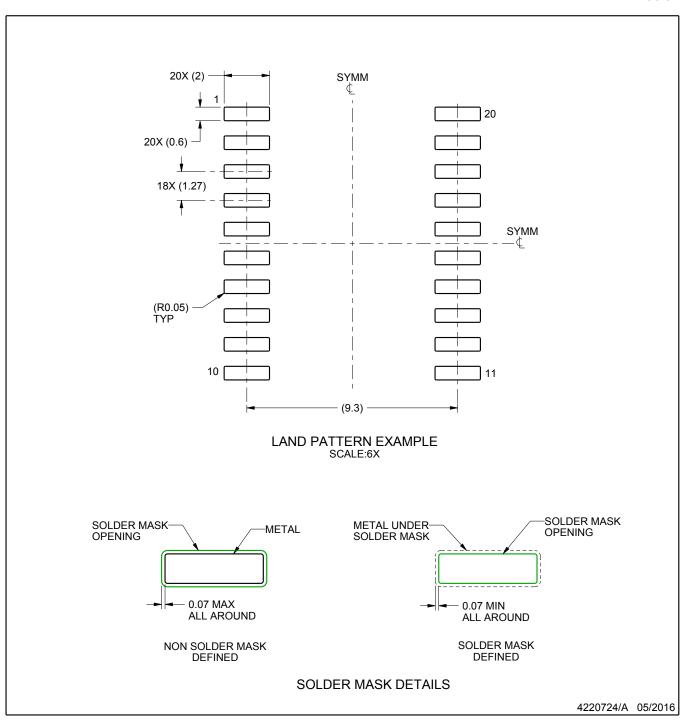
- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



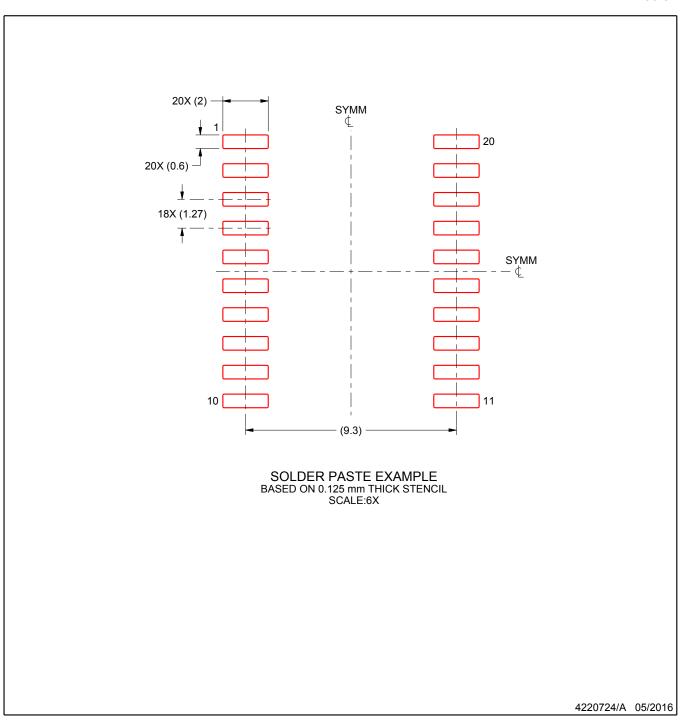
NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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